

Key Features

High Thermal Conductivity
Bonds Well to Most Substrates
Changes Color When Cured
Snap Cure at 150 °C
High Glass Transition Temperature
High Temperature Resistant
Long Pot Life
Meets NASA Outgassing Requirements
Resistant to Fuel, Lubricants, Water, and Weather
User-friendly Packaging

Uncured

Pot Life @ 25°C: 4 hours
Viscosity @ 25°C: 125,000 cPs
Shelf Life @ -40°C: 12 Months
Color: Blue
Thixotropic Index: 1.9

Cure Options

1 hour @ 120°C
5 minutes @ 150°C

Cured Properties

(Based on cure of 1 hour @ 120°C)

Color	Dark Tan
Shore D Hardness	97
Glass Transition Temp. (°C)	134
Density (g/cc)	2.62
Lap Shear 2024T3 Clad (psi)	2,500

Electrical Properties

Volume Resistivity (ohm-cm) 2.13E 16 @500 VDC

Product Description:

5302 is a blue, one-component, thermally conductive, precision mixed, degassed, and frozen adhesive. It is designed specifically for automated and manual dispensing. 5302 is used to encapsulate and underfil electronic components that require high thermal conductivity. 5302 is very clean and meets NASA outgassing requirements. The cured material can withstand high temperature environments and is resistant to fuel, lubricants, water, and weather.

Thermal Properties

(Based on cure of 1 hour @ 120°C)

Glass Transition Temp. (°C)	134
Thermal Conductivity (W/mK)	1.85
Degradation Temp. (°C)	275

Outgassing Properties

(Based on cured for 1 hour @ 120°C)

TML (%)	0.07
CVCM (%)	<0.01
WVR (%)	0.04

Acoustic Properties

Velocity (m/s)	3,450
Impedance (MRayles)	9.03
Loss (dB/cm-MHz)	-8.3
Density (g/cc)	2.62

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